

A structural and compositional analysis of a TiO_x diffusion barrier for indium Tin Oxide/Si contacts

Ok YW, Park WK, Kim HM, Kim KB, Kim D.
Metals and materials international
2008; 14(4):481-485

ARTICLE IDENTIFIERS

DOI: 10.3365/met.mat.2008.08.481

PMID: unavailable

PMCID: not available

JOURNAL IDENTIFIERS

LCCN: not available

pISSN: 1225-9438

eISSN: 1598-9623

OCLC ID: not available

CONS ID: not available

US National Library of Medicine ID: not available

This article was identified from a query of the SafetyLit database.